SPECIFICATION FOR APPROVAL

DESCRIPTION: Pitch 1.00mm ZIF FPO	C Connector, R/A, SMT Type Top Contact	
CUSTOMER PROD.NO/DWG.NO:		
E&T PROD.NO:	6901K-XXXN-XXX	
APPROVAL SHEET NO:		
E&T DWG. NO./DOCUMENT:	6901K-XXXN-XXX	
		DEV: A5

PLEASE RETURN TO US ONE COPY OF "SPECIFICATION FOR APPROVAL" WITH YOUR APPROVED SIGNATURES.

APPROVED SIGNATURES					



ENTERY INDUSTRIAL CO., LTD.
E&T ELECTRONICS (DONG GUAN) CO., LTD.
E&T ELECTRONICS (SU ZHOU) CO., LTD.
E&T ELECTRONICS (NANKEEN)CO.,LTD.

Title: Pitch 1.00mm ZIF FPC Connector, R/A, SMT Type Top Contact

RELEASE HISTORY Title: Pitch 1.00mm ZIF FPC Connector, R/A, SMT Type Top Contact				IT Type Top Contact		
A5	08,22,2012	This Document Contains Information That Is Proprietary To				
Rev	Description	E&T	E&T And Should Not Be Used Without Written Permission			
Document No.			Prepared By: Hil	l Chang	Date: 12,22,2008'	
6901K-XXXN-XXX		Checked By:	18美竹	Date: 8/2/		
		Approved By:	原美竹 (大)	Date: />		

GROUP AND TEST SEQUENCE

	Test of Examination				,	Test	Gr	oup)			
			В	С	D	Е	F	G	Н	I	J	K
1	Examination of Product	1,9	1,6	1,5	1,5	1,5	1,4	1,5	1,3	1,3	1,5	
2	Contact Resistance	2,6	2,5	2,4	2,4	2,4		2,4			2,4	
3	Insulation Resistance	3,7										
4	Dielectric Strength	4,8										
5	FPC Retention Force		3									
6	Terminal / Housing Retention Force											1
7	Durability		4									
8	Vibration			3								
9	Heat Resistance				3							
10	Cold Resistance					3						
11	Humidity	5										
12	Solder Ability						3		2			
13	Resistance To Soldering Heat									2		
14	Steam Aging						2					
15	Salt Spray							3				
16	Temperature Cycling										3	

PRODUCT SPECIFICATION

1. SCOPE:

This specification covers the pitch1.00 mm ZIF FPC connector series.

2. PRODUCT NAME AND PART NUMBER:

Product Name	E&T Part Number
1.00mm ZIF FPC Connector, R/A, SMT Type Top Contact	6901K-XXXN-XXX

3. RATINGS:

Item	S	tandard
Rated Voltage (MAX.)	50 V	(AC(rms/DC)
Rated Current (MAX.)	0.5A	(AC(IIIIs/DC)
Operating Temperature Range	-40 ⁰	C ~ +80 ⁰ C

^{*}Including terminal temperature rise

4.PERFORMANCE:

4- 1 Electrical Performance

	Item	Test Condition	Requirement
4-1-1	Contact Resistance	Test Current: 1 mA Max. Test Voltage: 20mV Max Test Method:EIA-364-06B	50 mΩ MAX.
4-1-2	Insulation Resistance	Test Voltage: 100V DC. Test Duration: 1 minutes.	Initial: 500 MΩ Min
	nesistance	Test Method:EIA-364-21C	Final: 100 M Ω Min.
4-1-3	Dielectric Strength	Test Voltage: 200V AC. Test Time: 60 sec. Test Method:EIA-364-09C	No Breakdown

4-2 Mechanical Performance

Item		Test Condition	Requirement	
4-2-1	FPC Retention Force	Test Speed: 25±3 mm/min.	0.035kgf	/ per pin
4-2-2	Terminal / Housing Retention Force	Test Speed: 25mm/min.	0.2kgf	(Min)
		Insert and withdraw actuator up to	Contact R	esistance
4-2-3	Durability	20cycles at the speed rate of less than 10 cycles/	Initial Value	\leq 20 m Ω
		minute.	Final Value	≤40 mΩ

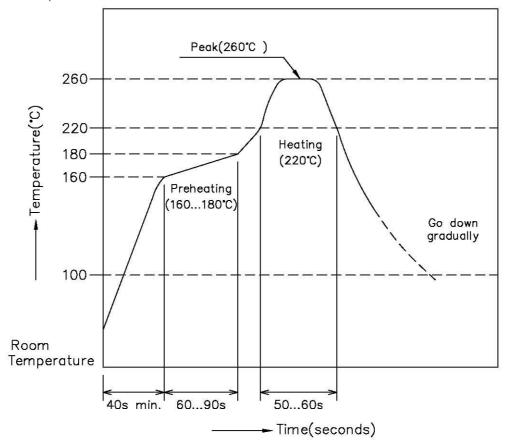
4-3 Environmental Performance and Others

	Item	Test Condition	Require	ment
		Amplitude: 1.5 mm Frequency range: 10~55~10 Hz in 1 minute	Appearance	No Damage
4-3-1	Vibration	Duration: 2 hours in each X.Y.Z axes Current: 100mA. Test Method:EIA-364-28D	Contact Resistance	≦80 mΩ
		Test Method.EIA-304-20D	Discontinuity	1µsec
4-3-2	Heat	Temperature: 80±2°C Duration: 96 hours	Appearance	No Damage
7-0-2	Resistance		Contact Resistance	≤80 mΩ
4-3-3	Cold	Temperature: $-40\pm2^{\circ}$ C Duration: 96 hours	Appearance	No Damage
4-0-0	Resistance		Contact Resistance	≦80 mΩ
		Temperature: 40±2°C Relative Humidity: 90~95%	Appearance	No Damage
4-3-4	Humidity	Duration: 96 hours	Contact Resistance	≤80 mΩ
	Trainiaity		Insulation Resistance	\geq 100M Ω
			Dielectric Strength	Must meet 4-1-3

Item		Test Condition	Requir	rement
4-3-5	Solder Ability	Soldering Time: 3±0.5 sec Solder Temperature: 245±5°C Test Method:EIA-364-52	Solder Wetting	95% Of Immersed Area Must Show No Voids, Pin Holes
4-3-6		Soldering Time : 10 ± 0.5 sec Solder Temperature : $260\pm5^{\circ}$ C Test Method:EIA-364-56C	Appearance	No Damage
		Steam Aging Temperature : 98±2°C Duration: 8 hours Solder Temperature : 235±5°C	Appearance	No Damage
4-3-7	Steam Aging	Soldering Time : 3±0.5 sec Test Method:EIA-364-17B	Solder Wetting	95% Of Immersed Area Must Show No Voids, Pin Holes
4-3-8	Salt Spray	Chamber Temperature : 35±2°C Air Tank Temperature : 47±1°C Salt Solution : 5 ± 0.5%	Appearance	No Damage
4-0-0	Gail Opiay	Duration: 48 hours Test Method:EIA-364-26B	Contact Resistance	\leq 80 m Ω
4-3-9	Temperature	5 cycles of : a) - 55 $\pm 3^{\circ}$ C 30 minutes b) +25 $\pm 3^{\circ}$ C 30 minutes	IAppearance	No Damage
7-0-9	Cycling	c)+ 85 $\pm 2^{\circ}$ C 30 minutes Test Method:EIA-364-31B	Contact Resistance	\leq 80 m Ω

5.INFRARED REFLOW CONDITION

- 1) Ascending time to preheating temperature 170°C shall be 40 seconds minimum.
- 2) Preheating shall be fixed at 160...180°C for 60...90 seconds.
- 3) Heating shall be fixed at 220°C for 50...60 seconds.
- 4) At 260±5°C peak shall be 10 seconds maximum.



FPC /FFC Connector Slip Lock Type Handling Precautions

This manual is to describe basic precautions. When there are doubtful points in use of, please contact E&T.

1. Common Handling Precautions

- Do not expose E&T's ZIF FPC/FFC connector, processing process product and processing product to corrosive substance, corrosive gas, high temperature and high humidity and direct sunshine. It causes corrosion of contact and deterioration of insulation performance of housing, etc., so that it causes motion defect of appliances.
- Do not apply external load to E&T's ZIF FPC/FFC connector, processing process product and processing product. Deformation and breakage, etc. occur, and it causes performance defect of.
- There may be slight differences in the housing coloring, but there will be no influence on the product's performance.
- Please add a stiffener on the flexible printed circuit (FPC/FFC) when you mount the connector onto FPC in order to prevent deformation of the FPC/FFC.
- Please do not conduct any "washing process" on the connector because it may damage the product's function.

2. PC Board Precautions

- Exercise caution when handling boards with the connectors installed. Do not apply any forces affecting soldered joints. (see figure 1).
- The mounting specification for coplanarity does not include the influence of warpage of the printed circuit board. (see figure 1).

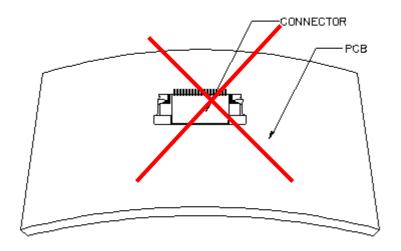


Figure 1.

3. Operation

FPC/FFC Insertion Procedure.

• 1) Connector installed on the board. Seize the actuator(Lock) to pull out. Use thumb and index finger. (see figure 2).

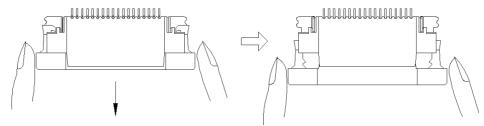


Figure 2.

• 2) Assure that the FPC/FFC is fully inserted parallel to mounting surface. (see figure 3)

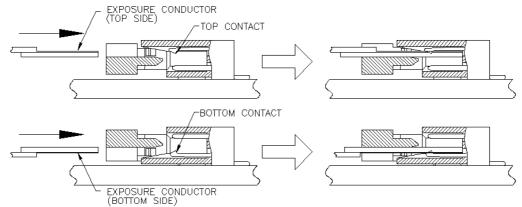


Figure 3.

• 3) Push the actuator(Lock) until firmly closed. It is critical that the inserted FPC is not moved and remains fully inserted. Should the FPC be moved, open the actuator(Lock) and repeat the process, starting with Step 1(see figure 4).

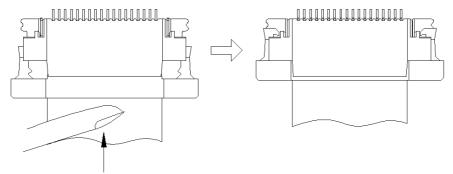


Figure 4.

FPC/FFC Removal.

- 1) Seize the actuator(Lock) to pull out. Use thumb and index finger. (see figure 5).
- 2) Carefully withdraw the FPC/FFC. (see figure 5).

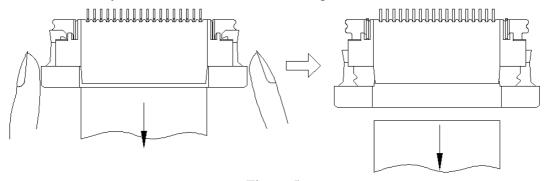


Figure 5.

4. Precautions When Inserting or Withdrawal FPC/FFC

• FPC/FFC to be insertion and withdrawal at an angle of about 15°, and the FPC/FFC should be inserted firmly all the way to the back. (see figure 6).

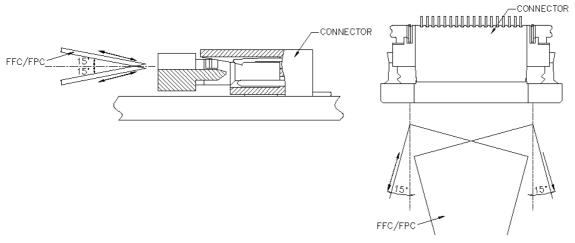


Figure 6.

- If necessary, please fix the FPC/FFC directly on the chassis. Also, please avoid pulling the FPC/FFC vertically or twisting the FPC back and force horizontally while it is inserted in the connector(see figure 7).
- Forming processing is conducted to FPC so as not to load force to connector. (see figure 7).

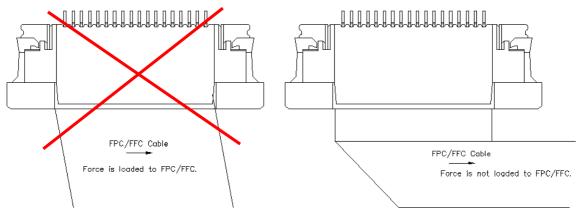


Figure 7.

RELEASE HISTORY

Rev.	Revisions	Date	Executor	Description
A2	RE201108011	Aug-19-2011	Well	ADD Handling Precautions
A3	RE201111028	DEC-08-2011	Juno	Modify Handling Precautions
				Cancel Packaging
A4	RE201206006	JUN-18-2012	JIMMY	CHANGE FPC Retention Force
A5	RE201207023	AUG-22-2012	KAZ	MATERIAL CHANGE